

REMARKS

Claims 11-18 and 23-27 are pending in this application. Claims 19 and 20 stand withdrawn.

By this Amendment, independent claims 11 and 23 are amended for better clarity. See the specification at, for example, Fig. 1. Claims 26 and 27 are added to recite additional features disclosed in the specification at, for example, Fig. 1 and page 8, lines 24-26.

Reconsideration of the application is respectfully requested.

The Office Action rejects claims 11-17 and 23-25 under 35 U.S.C. §103(a) over U.S. Patent 6,891,248 to Akram et al. ("Akram") in view of U.S. Patent 6,323,542 to Hashimoto ("Hashimoto") and U.S. Patent 6,534,386 to Irie ("Irie"); and rejects claim 18 under 35 U.S.C. §103(a) over Akram in view of Hashimoto and Irie, and further in view of U.S. Patent 6,242,156 to Teng ("Teng"). These rejections are respectfully traversed.

Claim 11 is amended to recite forming a second resin layer over the first resin layer and in direct contact with the semiconductor wafer. Claim 23 is similarly amended. The applied references do not disclose or suggest this feature.

In particular, as indicated in the Office Action at page 3, 13-16, Hashimoto does not disclose or suggest a second resin layer that is in direct contact with a semiconductor wafer. Also, Akram, Irie and Teng do not disclose or suggest such a feature. Therefore, Akram, Hashimoto, Irie and Teng, either individually or in combination, do not disclose or suggest the subject matter recited in claims 11 and 23, and claims 12-18, 24 and 25 depending therefrom. Accordingly, withdrawal of the rejection of claims 11-18 and 23-25 under 35 U.S.C. §103(a) is respectfully requested.

Claims 19 and 20 depend from claim 11. Thus, rejoinder and allowance of claims 19 and 20 are respectfully requested.

New claims 26 and 27 are patentable over the applied references. For example, the applied references do not disclose or suggest forming a second resin layer over the first resin layer and in direct contact with the passivation film, as recited in claim 26, and similarly recited in claim 27.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 11-20 and 23-27 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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